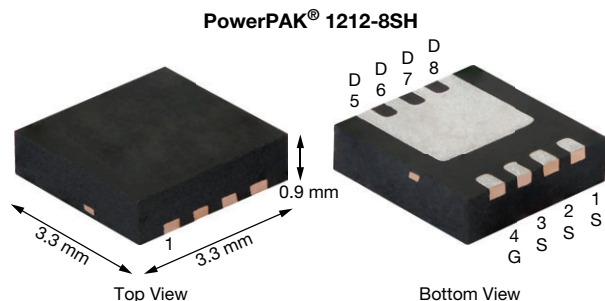


P-Channel 30 V (D-S) MOSFET



PRODUCT SUMMARY	
V_{DS} (V)	-30
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -10$ V	0.0123
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5$ V	0.0222
Q_g typ. (nC)	20.5
I_D (A) ^{d, g}	-35
Configuration	Single

ORDERING INFORMATION	
Package	PowerPAK 1212-8
Lead (Pb)-free and halogen-free	SiSH617DN-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	-30	V
Gate-source voltage		V_{GS}	± 25	
Continuous drain current ($T_J = 150$ °C)	$T_C = 25$ °C	I_D	-35 ^d	A
	$T_C = 70$ °C		-35 ^d	
	$T_A = 25$ °C		-13.9 ^{a, b}	
	$T_A = 70$ °C		-11.1 ^{a, b}	
Pulsed drain current		I_{DM}	-60	
Continuous source-drain diode current	$T_C = 25$ °C	I_S	-35 ^d	
	$T_A = 25$ °C		-3 ^{a, b}	
Avalanche current		I_{AS}	-29	
Single-pulse avalanche energy		E_{AS}	42	mJ
Maximum power dissipation	$T_C = 25$ °C	P_D	52	W
	$T_C = 70$ °C		33	
	$T_A = 25$ °C		3.7 ^{a, b}	
	$T_A = 70$ °C		2.4 ^{a, b}	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) ^{e, f}			260	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^{a, c}	$t \leq 10$ s	R_{thJA}	26	33	°C/W
Maximum junction-to-case	Steady state	R_{thJC}	1.9	2.4	

Notes

- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- Maximum under steady state conditions is 81 °C/W
- Package limited
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8SH is a leadless package within the PowerPAK 1212-8 package family. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Based on $T_C = 25$ °C

FEATURES

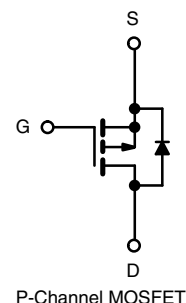
- TrenchFET® power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Notebook battery charging
- Notebook adapter switch



RoHS
COMPLIANT
HALOGEN
FREE



P-Channel MOSFET



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-30	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = -250 μA	-	-25	-	mV/°C
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J		-	4.7	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-1.2	-	-2.5	V
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 25 V	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V	-	-	-1	μA
		V _{DS} = -30 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-5	
On-state drain current ^a	I _{D(on)}	V _{DS} ≥ -10 V, V _{GS} = -10 V	-30	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -10 V, I _D = -13.9 A	-	0.0103	0.0123	Ω
		V _{GS} = -4.5 V, I _D = -10.3 A	-	0.0185	0.0222	
Forward transconductance ^a	g _{fs}	V _{DS} = -15 V, I _D = -13.9 A	-	35	-	S
Dynamic ^b						
Input capacitance	C _{iss}	V _{DS} = -15 V, V _{GS} = 0 V, f = 1 MHz	-	1800	-	pF
Output capacitance	C _{oss}		-	370	-	
Reverse transfer capacitance	C _{rss}		-	312	-	
Total gate charge	Q _g	V _{DS} = -15 V, V _{GS} = -10 V, I _D = -13.9 A	-	39	59	nC
		V _{DS} = -15 V, V _{GS} = -4.5 V, I _D = -13.9 A	-	20.5	31	
Gate-source charge	Q _{gs}		-	6	-	
Gate-drain charge	Q _{gd}		-	11	-	
Gate resistance	R _g	f = 1 MHz	0.4	2	4	Ω
Turn-on delay time	t _{d(on)}	V _{DD} = -15 V, R _L = 1.35 Ω I _D ≅ -11.1 A, V _{GEN} = -10 V, R _g = 1 Ω	-	11	22	ns
Rise time	t _r		-	9	18	
Turn-off delay time	t _{d(off)}		-	32	50	
Fall time	t _f		-	9	18	
Turn-on delay time	t _{d(on)}	V _{DD} = -15 V, R _L = 1.35 Ω I _D ≅ -11.1 A, V _{GEN} = -4.5 V, R _g = 1 Ω	-	40	60	
Rise time	t _r		-	43	65	
Turn-off delay time	t _{d(off)}		-	30	45	
Fall time	t _f		-	11	22	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-35	A
Pulse diode forward current	I _{SM}		-	-	-60	
Body diode voltage	V _{SD}	I _S = -11.1 A, V _{GS} = 0 V	-	-0.8	-1.2	V
Body diode reverse recovery time	t _{rr}	I _F = -11.1 A, di/dt = 100 A/μs, T _J = 25 °C	-	33	50	ns
Body diode reverse recovery charge	Q _{rr}		-	30	45	nC
Reverse recovery fall time	t _a		-	18	-	ns
Reverse recovery rise time	t _b		-	16	-	

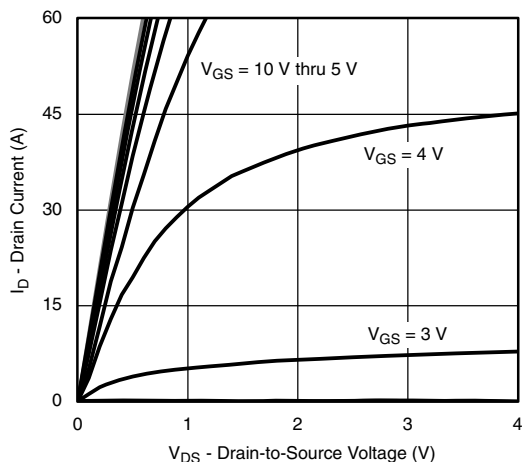
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

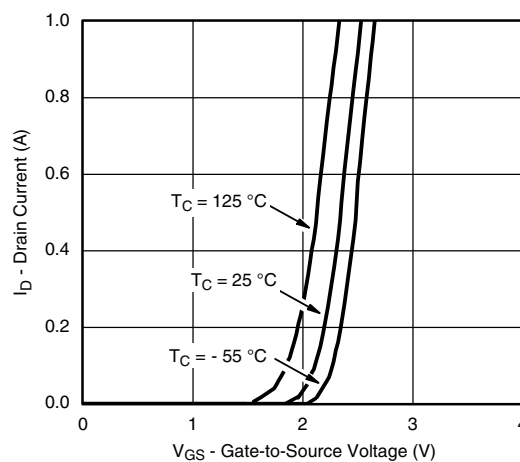
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



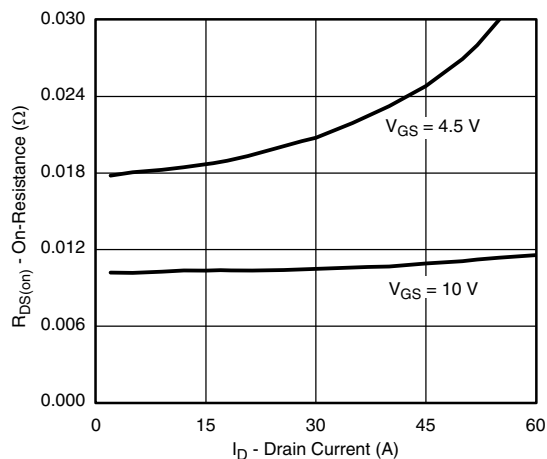
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



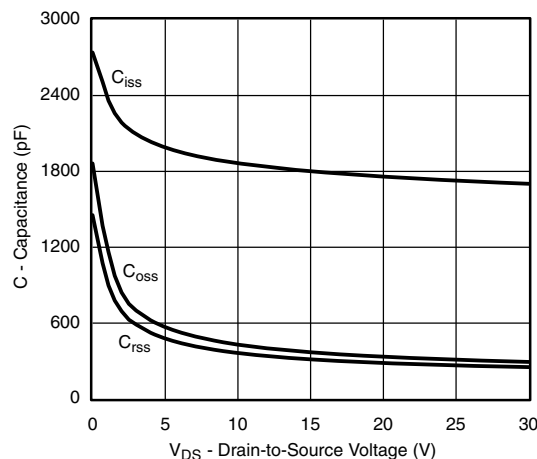
Output Characteristics



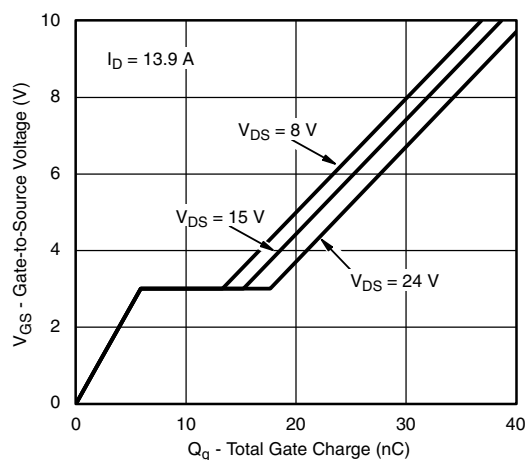
Transfer Characteristics



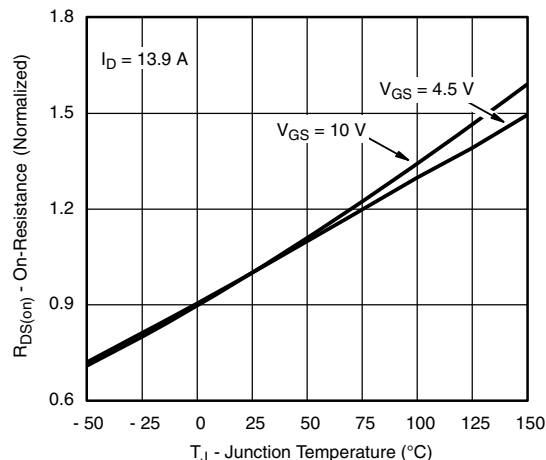
On-Resistance vs. Drain Current



Capacitance



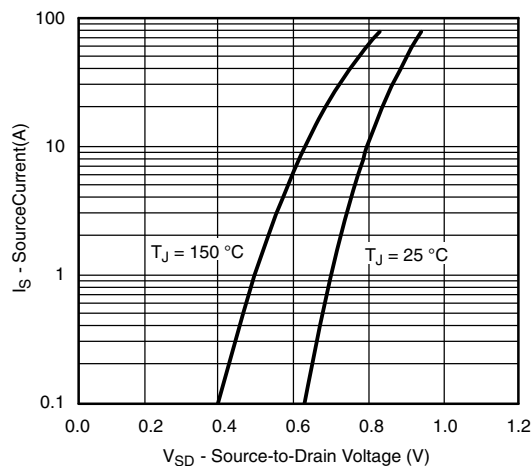
Gate Charge



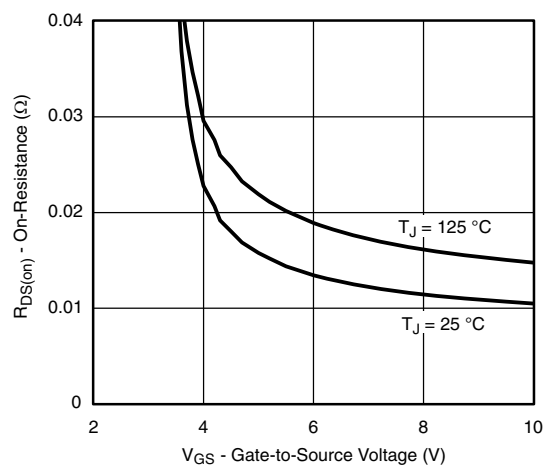
On-Resistance vs. Junction Temperature



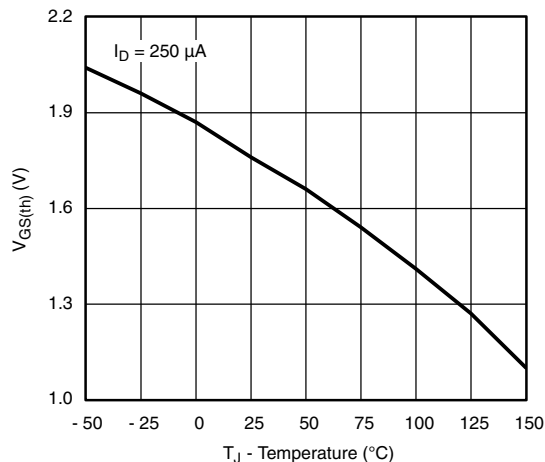
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



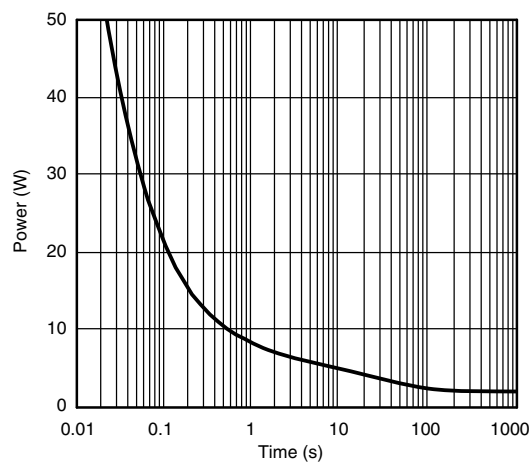
Source-Drain Diode Forward Voltage



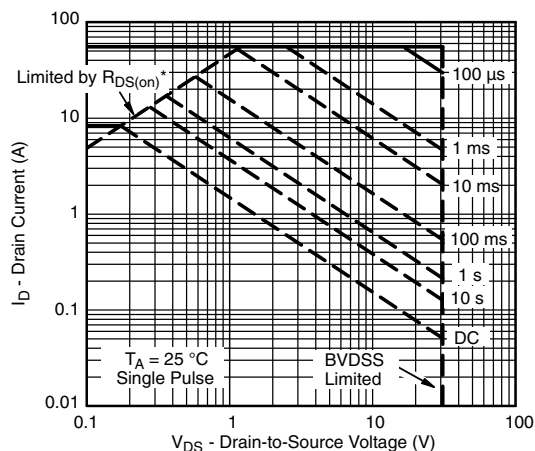
On-Resistance vs. Gate-to-Source Voltage



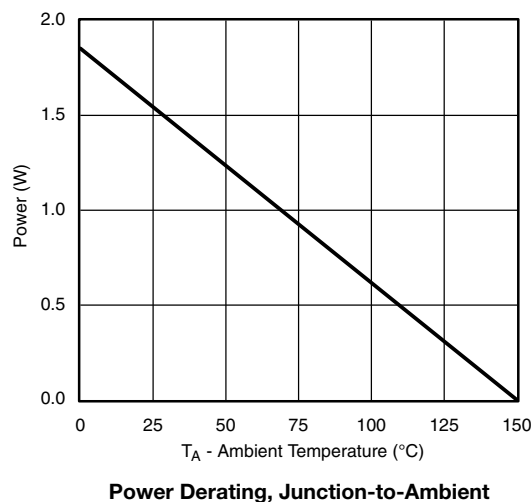
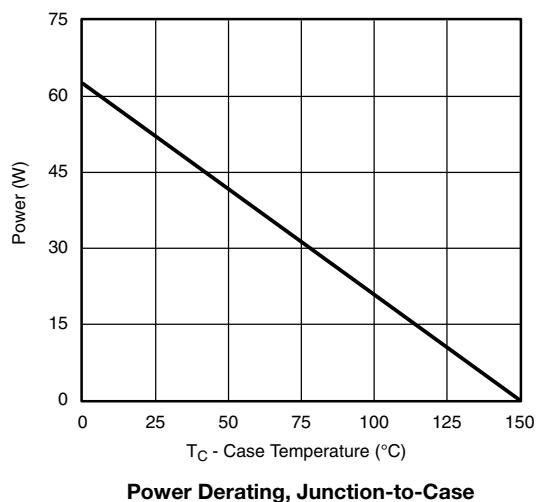
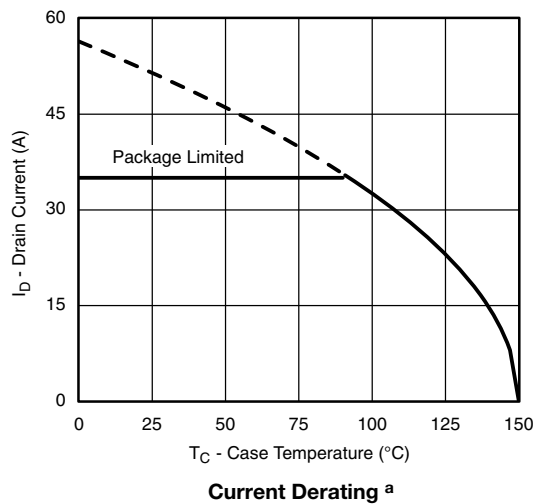
Threshold Voltage



Single Pulse Power, Junction-to-Ambient



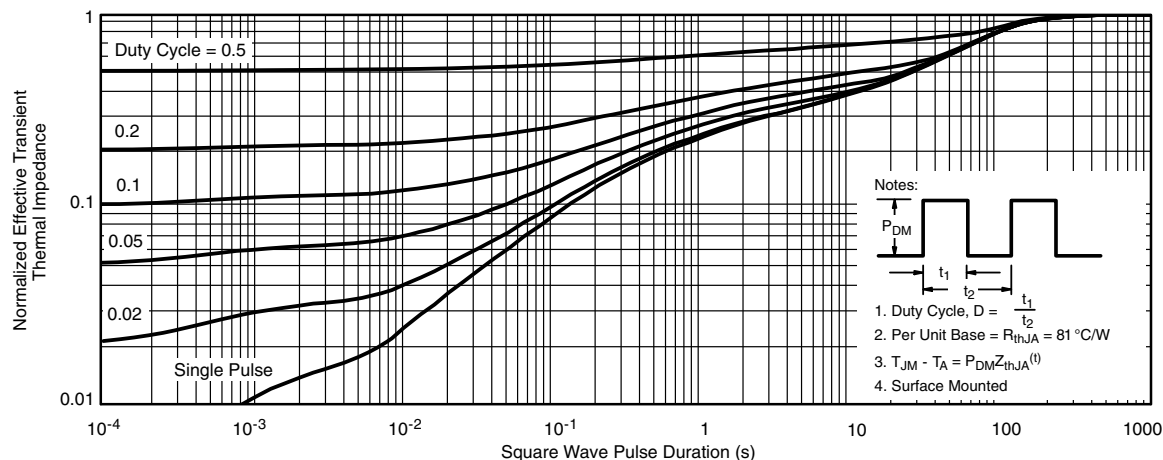
Safe Operating Area

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Note

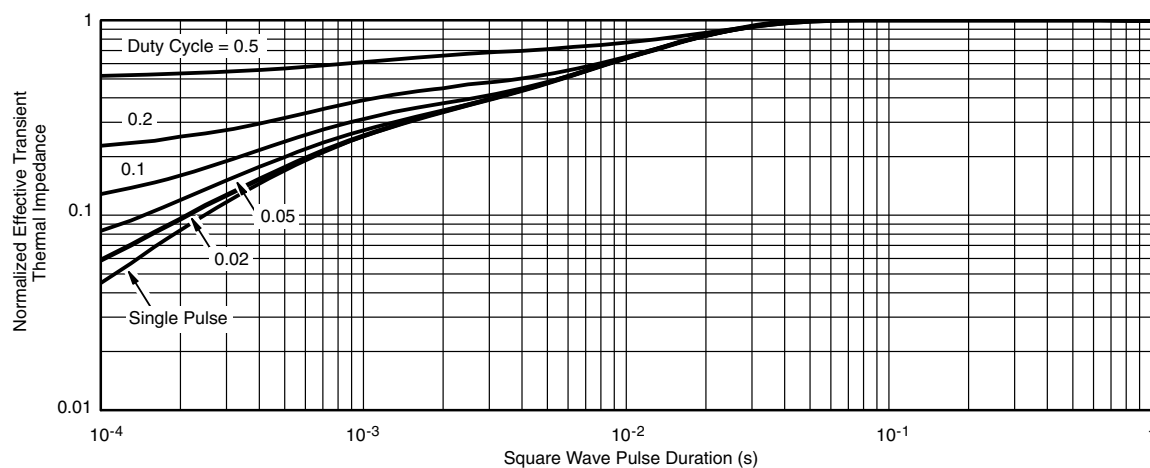
- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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Case Outline for PowerPAK® 1212-SWLH and PowerPAK® 1212-8SH



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.82	0.90	0.98	0.032	0.035	0.038
A1	0.00	-	0.05	0.000	-	0.002
A3	0.20 ref.			0.008 ref.		
b	0.25	0.30	0.35	0.010	0.012	0.014
D	3.20	3.30	3.40	0.126	0.130	0.134
D1	2.15	2.25	2.35	0.085	0.089	0.093
E	3.20	3.30	3.40	0.126	0.130	0.134
E1	1.60	1.70	1.80	0.063	0.067	0.071
e	0.65 bsc.			0.026 bsc.		
K	0.76 ref.			0.030 ref.		
K1	0.41 ref.			0.016 ref.		
L	0.33	0.43	0.53	0.013	0.017	0.021
Z	0.525 ref.			0.021 ref.		
ECN: S20-0930-Rev. C, 07-Dec-2020						
DWG: 6062						

RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads
Dimensions in Inches/(mm)

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